

Part Number: **DMG6968U-p, DMG3415U-p, DMG2301U-p**  
Weight (mg): 8.88

p = package indicator  
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.45	0.31	1000000	34489
Leadframe	CDA-194	Cu	7440-50-8	97.40%	29.62	2.63	974000	288534
		Fe	7439-89-6	2.40%			24000	7110
		P	7723-14-0	0.08%			800	237
		Zn	7440-66-6	0.12%			1200	355
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.16	0.10	1000000	11643
Bond Wire	Copper Wire	Cu	7440-50-8	100.00%	1.06	0.09	1000000	10618
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	60.32	5.36	690000	416241
		Epoxy Resin	29690-82-2	14.00%			140000	84455
		Phenol Resin	9003-35-4	7.00%			70000	42227
		Mg(OH)2	1309-42-8	8.00%			80000	48260
		C	1333-86-4	0.20%			2000	1206
		others (wax, catalyst, coupling agent)	----	1.80%			18000	10858
Die attached epoxy	84-1 LMISR4	Ag	7440-22-4	75.00%	1.50	0.13	750000	11249
		epoxy resin	Trade secret	20.00%			200000	3000
		curing agent & hardener	Trade secret	5.00%			50000	750
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.88	0.26	1000000	28769
Total					100.00	8.88		1000000

Tolerance ±10%

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\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101.

This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethylhexyl)phthalate (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

Part Number: **DMG4413LSS-P**  
Weight (mg): 76.90

p = package indicator  
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	5.18	3.98	1000000	51756
Leadframe	CDA-194	Cu	7440-50-8	97.40%	50.75	39.03	974000	494344
		Fe	7439-89-6	2.40%			24000	12181
		P	7723-14-0	0.08%			800	406
		Zn	7440-66-6	0.12%			1200	609
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.93	0.71	1000000	9285
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	1.28	0.98	1000000	12755
Encapsulation	EME-G700	Epoxy Resin	-----	7.50%	37.57	28.89	75000	28180
		Phenol Resin	-----	5.00%			50000	18787
		Bismuth/Bismuth compound	-----	0.05%			500	188
		SiO2	60676-86-0	86.95%			869500	326704
		C	1333-86-4	0.50%			5000	1879
Die Attach Epoxy	84-1 LMISR4	Ag	7440-22-4	75.00%	2.08	1.60	750000	15621
		epoxy resin	Trade secret	20.00%			200000	4166
		curing agent & hardener	Trade secret	5.00%			50000	1041
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.21	1.70	1000000	22100
<b>Total</b>					<b>100.00</b>	<b>76.90</b>		<b>1000000</b>

Tolerance ±10%

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This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)
<b>REACH SVHCs:</b>	
Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

Part Number: **DMG1016V-p**  
Weight (mg): 3.05

p = package indicator  
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	5.78	0.18	1000000	57818
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	34.59	1.06	992600	343302
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	934
		Sn	7440-31-5	0.25%			2500	865
		Zn	7440-66-6	0.22%			2200	761
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.52	0.02	1000000	5173
Bond Wire	Gold	Au	7440-57-5	100.00%	1.29	0.04	1000000	12899
Encapsulation	CEL-1702HF-9	SiO2	60676-86-0	87.30%	55.70	1.70	873000	486232
		Epoxy Resin	29690-82-2	5.00%			50000	27848
		Phenol Resin	26834-02-6	5.00%			50000	27848
		Aromatic poly-phosphate	----	2.50%			25000	13924
		C	1333-86-4	0.20%			2000	1114
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.13	0.07	1000000	21281
				Total	100.00	3.05		1000000

Tolerance ±10%

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This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

Part Number: **DMG6968UDM-p, DMG9926UDM-p**  
Weight (mg): 16.55

p = package indicator  
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.16	0.69	1000000	41574
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	41.50	6.87	992600	411974
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	1121
		Sn	7440-31-5	0.25%			2500	1038
		Zn	7440-66-6	0.22%			2200	913
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.80	0.13	1000000	8041
Bond Wire	Copper	Cu	7440-50-8	100.00%	1.57	0.26	1000000	15682
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	45.52	7.54	873000	397395
		Epoxy Resin	29690-82-2	5.00%			50000	22760
		Phenol Resin	26834-02-6	5.00%			50000	22760
		Aromatic poly-phosphate	----	2.50%			25000	11380
		C	1333-86-4	0.20%			2000	910
Die Attach Epoxy	84-1 LMISR4	Ag	7440-22-4	75.00%	1.74	0.29	750000	13071
		epoxy resin	Trade secret	20.00%			200000	3486
		curing agent & hardener	Trade secret	5.00%			50000	871
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	4.70	0.78	1000000	47023
				Total	100.00	16.55		1000000

Tolerance ±10%

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Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

Part Number: **DMG6968UTS-p, DMG8822UTS-p**  
Weight (mg): 40.81

p = Packaging Code  
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.69	0.69	1000000	16863
Leadframe	C7025	Cu	7440-50-8	95.90%	41.57	16.97	959000	398701
		Si	7440-21-3	0.73%			7250	3014
		Ni	7440-02-0	3.20%			32000	13304
		Mg	7439-95-4	0.18%			1750	728
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.70	0.69	1000000	16981
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	0.99	0.41	1000000	9941
Encapsulation	EME-G700	Epoxy Resin	-----	7.50%	53.24	21.73	75000	39927
		Phenol Resin	-----	5.00%			50000	26618
		Bismuth/Bismuth compound	-----	0.05%			500	266
		SiO2	60676-86-0	86.95%			869500	462889
		C	1333-86-4	0.50%			5000	2662
Die Attach Epoxy	8352L	Ag	7440-22-4	66.50%	0.59	0.24	665000	3894
		Epoxy Resin	----	20.00%			200000	1171
		Aliphatic anhydride	-----	7.50%			75000	439
		2-Butoxyethyl acetate	112-07-2	3.00%			30000	176
		Polymeric material	----	3.00%			30000	176
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.22	0.09	1000000	2249
					<b>Total</b>	<b>100.00</b>	<b>40.81</b>	<b>1000000</b>

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Hexavalent chromium compounds	Radioactive Substances
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Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentaoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate